

TITLE: HIGH-DENSITY PLASMA DEPOSITION PROCESS FOR FABRICATING A TOP CLAD FOR PLANAR LIGHTWAVE CIRCUIT DEVICES INVENTOR(S): Fan ZHONG, Jonathan G. BORNSTEIN USSN: 09/874,434 Attorney Docket #: LWM-A105

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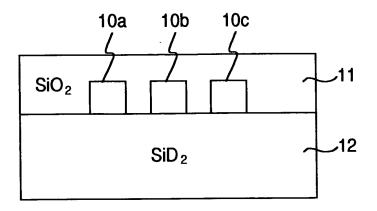


Fig. 1 (Prior Art)



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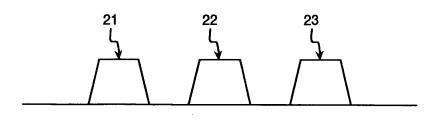


Fig. 2A (Prior Art)

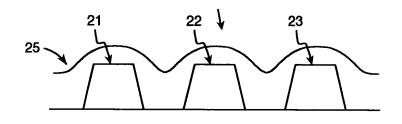


Fig. 2B (Prior Art)

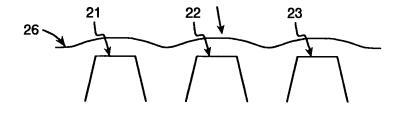


Fig. 2C (Prior Art)



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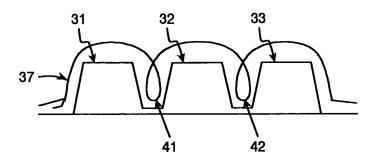


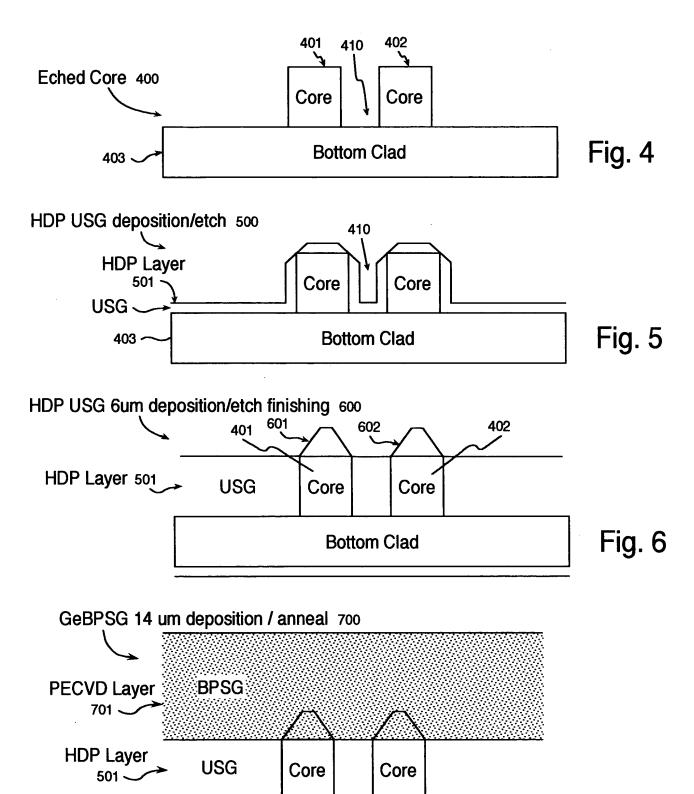
Fig. 3 (Prior Art)



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Bottom Clad

Fig. 7



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One Step HDP deposition and anneal (BPSG) with One Step PECVD deposition and anneal (BPSG)

PECVD Layer
701 — BPSG
HDP Layer
801 — BPSG
Core
Bottom Clad

Fig. 8